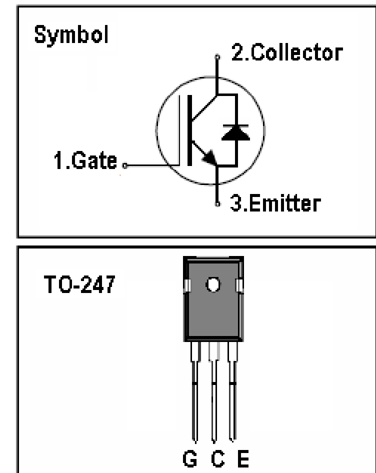
IGBT



Features

- 1200V,40A ,$V_{CE(sat)(typ.)}$=1.9V@V_{GE}=15V
- SPT （Soft Punch Through） technology
- Lower losses
- Higher system efficiency
- Excellent short-circuit capability
- Square RBSOA

General Description

DAXIN's IGBTs offer lower losses and higher energy
for application such as motor drive ,UPS, inverter and other
soft switching applications.

Absolute Maxinmun Ratings

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	±30	V
I_C	Continuous Collector Current (T_C=25 ℃)	80	A
	Continuous Collector Current (T_C=100℃)	40	A
I_{CM}	Pulsed Collector Current (Note 1)	160	A
I_F	Diode Continuous Forward Current (T_C=100 ℃)	40	A
I_{FM}	Diode Maximum Forward Current (Note 1)	160	A
t_{sc}	Short Circuit Withstand Time	10	us
Isc	Short Circuit Current	160	A
P_D	Maximum Power Dissipation (T_C=25 ℃)	378	W
	Maximum Power Dissipation (T_C=100℃)	151	W
T_J	Operating Junction Temperature Range	-55 to +150	℃
T_{STG}	Storage Temperature Range	-55 to +150	℃

Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	0.33	℃/ W
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	0.65	℃/ W
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	40	℃/ W

Electrical Characteristics (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	V_{GE}= 0V, I_C= 250uA	1200	-	-	V
I_{CES}	Collector-Emitter Leakage Current	V_{CE}= 1200V, V_{GE}= 0V	-	-	250	uA
I_{GES}	Gate Leakage Current, Forward	V_{GE}=30V, V_{CE}= 0V	-	-	100	nA
	Gate Leakage Current, Reverse	V_{GE}= -30V, V_{CE}= 0V	-	-	-100	nA
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE}= V_{CE}, I_C= 250uA	4.5	5.0	5.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	V_{GE}=15V, I_C= 40A	-	1.9	2.2	V
Qg	Total Gate Charge	V_{CC}=960V V_{GE}=15V I_C=40A	-	230		nC
Qge	Gate-Emitter Charge		-	25		nC
Qgc	Gate-Collector Charge		-	150		nC
$t_{d(on)}$	Turn-on Delay Time	V_{CC}=600V V_{GE}=15V I_C=40A R_G=10Ω Inductive Load T_C=25℃	-	29	-	ns
t_r	Turn-on Rise Time		-	76	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	304	-	ns
t_f	Turn-off Fall Time		-	163	-	ns
Eon	Turn-on Switching Loss		-	3.95	-	mJ
Eoff	Turn-off Switching Loss		-	2.70	-	mJ
Ets	Total Switching Loss		-	6.65	-	mJ
Cies	Input Capacitance	V_{CE}=25V V_{GE}=0V f = 1MHz	-	1600	-	pF
Coes	Output Capacitance		-	270	-	pF
Cres	Reverse Transfer Capacitance		-	165	-	pF
R_{Gint}	Integrated gate resistor	f=1M;Vpp=1V		4.5		Ω

Electrical Characteristics of Diode (T_C=25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	I_F=40A	-	1.9	2.2	V
t_{rr}	Diode Reverse Recovery Time	V_{CE} = 600V I_F= 40A dI_F/dt = 500A/us	-	130		ns
I_{rr}	Diode peak Reverse Recovery Current		-	25		A
Q_{rr}	Diode Reverse Recovery Charge		-	2100		nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature